

Application No. 10/700,136  
Response to Office Action

Customer No. 01933

Amendments to the Specification

Please amend the paragraph at page 10, line 19 to page 11,  
line 2 as follows:

A copper bump electrode 10 is formed on the upper surface of a connecting pad portion of each distribution wire 8. On the upper surface of the protective film 5 ~~including and~~ the distribution wires 8, an encapsulating film 11 made of an organic resin such as an epoxy-based resin is formed such that the upper surface of the encapsulating film 11 is leveled with the upper surfaces of the bump electrodes 10. Accordingly, ~~these~~ the upper surfaces of the bump electrodes 10 are exposed. A solder ball 12 is formed on the upper surface of each bump electrode 10.